

WHAT IS CLAIMED IS:

1. A molding obtained by heating a hydrosilylated polymer at a temperature higher than the softening point or melting point thereof, said hydrosilylated polymer being obtained by reacting at least one hydridosilsesquioxane compound of the following formula (1):



- wherein n is an integer of 4-1000, with at least one divinylsiloxane compound of the following formula (2):



- wherein R and R' are independently selected from alkyl groups, substituted alkyl groups, aryl groups and substituted aryl groups, and q and q' are each an integer of 0 or more.

2. A molding as claimed in claim 1, wherein said heating is performed under a reduced pressure.

3. A molding as claimed in claim 1, wherein said heating comprises (b1) heating the hydrosilylated polymer at a temperature higher than the softening point or melting point thereof under a reduced pressure, (b2) then heating the hydrosilylated polymer at ambient pressure, and (b3) heating the product obtained in step (b2) in the mold cavity to complete the curing of the hydrosilylated polymer, steps (b1) and (b2) being successively repeated at least twice before step (b3).

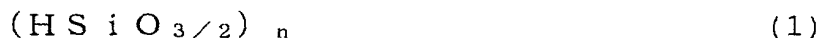
4. A molding as claimed in claim 1, wherein n in the formula (1) of said hydridosilsesquioxane is 8.

5. A molding as claimed in claim 1, wherein said

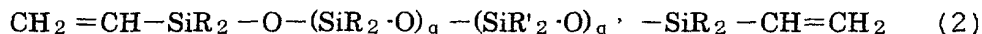
heating is at 50-250°C.

6. A method of preparing a molding, comprising the steps of:

- 5 (a) providing a hydrosilylated polymer obtained by reacting at least one hydridosilsesquioxane compound of the following formula (1):



- wherein n is an integer of 4-1000, with at least one
10 divinylsiloxane compound of the following formula (2):



- wherein R and R' are independently selected from alkyl groups, substituted alkyl groups, aryl groups and substituted aryl groups, and q and q' are each an integer
15 of 0 or more, and

(b) heating the hydrosilylated polymer at a temperature higher than the softening point or melting point thereof in a mold cavity to cure the polymer.

- 20 7. A method as claimed in claim 6, wherein step (b) is performed under a reduced pressure.

8. A method as claimed in claim 6, wherein step (b) comprises (b1) heating the hydrosilylated polymer at a
25 temperature higher than the softening point or melting point thereof under a reduced pressure, (b2) then heating the hydrosilylated polymer at ambient pressure, and (b3) heating the product obtained in step (b2) in the mold cavity to complete the curing of the hydrosilylated
30 polymer, steps (b1) and (b2) being successively repeated at least twice before step (b3).

9. A method as claimed in claim 6, wherein n in the formula (1) of said hydridosilsesquioxane is 8.

10. A method as claimed in claim 6, wherein said heating is at 50-250°C.